

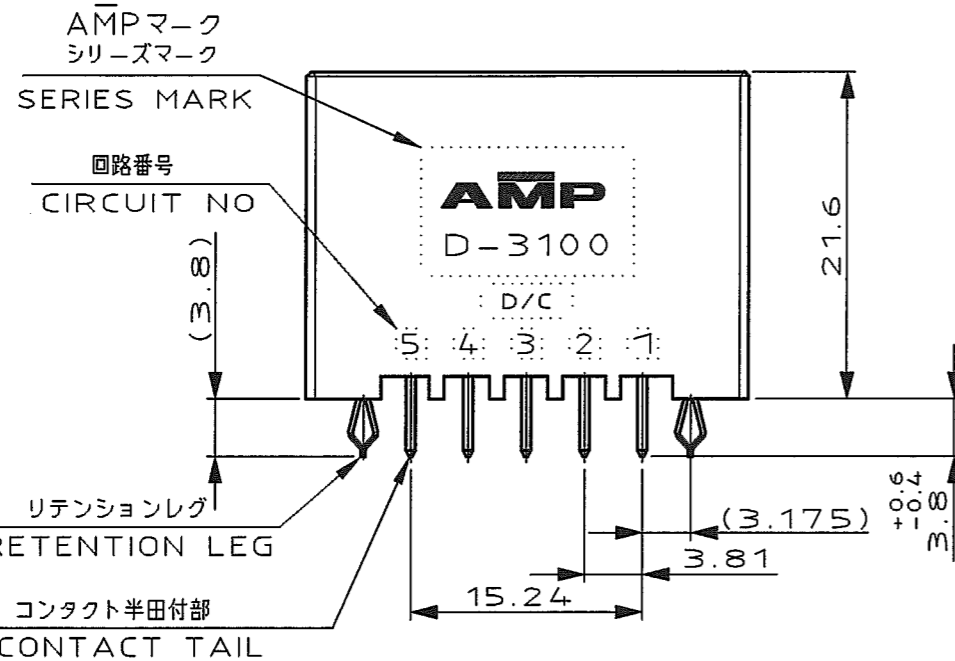
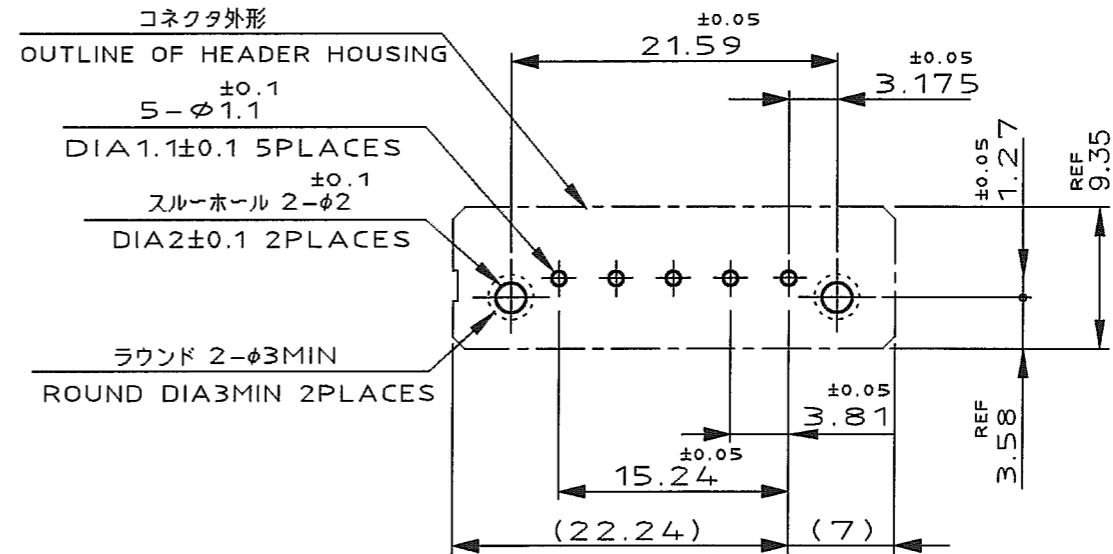
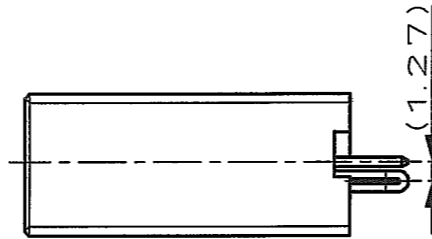
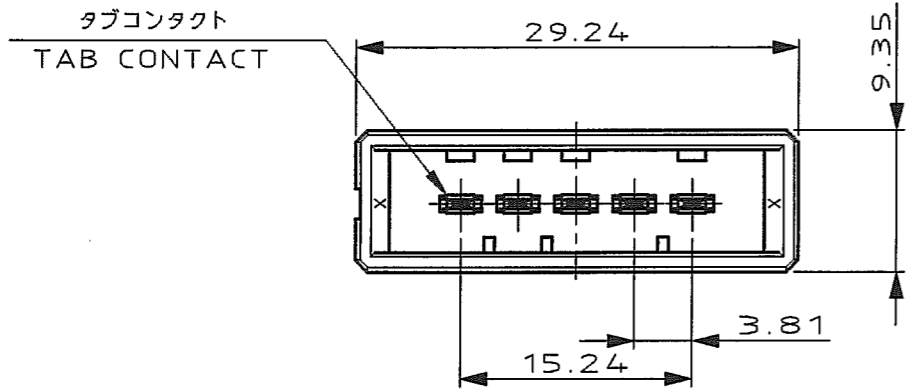
NUMBER 178315



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



コネクタ外形
OUTLINE OF HEADER HOUSING

推奨基板取付け寸法
PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- △ 1. FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- △ 2. FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- △ 3. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- △ 4. FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- △ 5. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
コンタクト: 銅合金
リテンションレグ: 銅合金
- △ 1. めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN金めっき
- △ 2. めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN金めっき
- △ 3. めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき
- △ 4. めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
- △ 5. めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上にスズめっき

△6	△4	1-178315-5
△6	△3	1-178315-3
△6	△2	1-178315-2
(FINISH)		製品番号 (PART NO.)

E1	REVISED PER ECO-11-005030	RK	HMR	23MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA		NAME	
mm (AWG)		mm		5 POS SINGLE ROW VERTICAL HDR ASS'Y FOR DYNAMIC D-3100	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	SIZE LOC NUMBER
DR. 19 APR 94 N. Matsubara		DE. 19 APR 94 N. Matsubara		10% ±0.3	A3 J C=178315
CHK. 20 APR 94 S. MANABE		APP. 20 APR 94 S. MANABE		10% 30% ±0.4	SCALE REV. SHEET
				30% 100% ±0.45	2-1 E1 1 OF 1
				角 度 ±3'	



Mouser Electronics

Authorized Distributor

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[1-178315-2](#)